

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chia-Wei Su</td> <td>11/09/2009</td> </tr> <tr> <td>Ju-Lin Huang</td> <td>11/17/2009</td> </tr> <tr> <td>Keko-Chun Liang</td> <td>11/17/2009</td> </tr> </tbody> </table>		Name	Execution Date	Chia-Wei Su	11/09/2009	Ju-Lin Huang	11/17/2009	Keko-Chun Liang	11/17/2009		
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>Novatek Microelectronics Corp.</td> </tr> <tr> <td>Street Address:</td> <td>2F, No. 13, Innovation Road I,</td> </tr> <tr> <td>Internal Address:</td> <td>Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsinchu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	Novatek Microelectronics Corp.	Street Address:	2F, No. 13, Innovation Road I,	Internal Address:	Science-Based Industrial Park	City:	Hsinchu	State/Country:	TAIWAN
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CORRESPONDENCE DATA											
Fax Number: (949)660-0809 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Email: usa@jcipgroup.com.tw Correspondent Name: JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE Address Line 1: 7F-1, NO.100, ROOSEVELT RD., SEC.2 Address Line 4: Taipei, TAIWAN 100											
ATTORNEY DOCKET NUMBER:	32265-US-PA										
NAME OF SUBMITTER:	Belinda Lee										
Total Attachments: 2 source=32265_a#page1.tif source=32265_a#page2.tif											

CH \$40.00 12687892

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PATENT
REEL: 023880 FRAME: 0992

NVT-2009-086
32265-US-PA

ASSIGNMENT

WHEREAS,

1. Chia-Wei Su
2. Ju-Lin Huang
3. Keko-Chun Liang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **AMPLIFIER CIRCUIT WITH OVERSHOOT SUPPRESSION**

☐ Filed: Serial No.

☒ Executed concurrently with the execution of this instrument

WHEREAS, Novatek Microelectronics Corp.
of 2F, No. 13, Innovation Road I, Science-Based Industrial Park, Hsinchu, Taiwan,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chia-Wei Su
Sole or First Joint Inventor: Chia-Wei Su

Date: 2009.11.09

Signature: Ju-Lin Huang
Second Joint Inventor (if any): Ju-Lin Huang

Date: 2009.11.17

Signature: Keko-Chun Liang
Third Joint Inventor (if any): Keko-Chun Liang

Date: 2009.11.17